

Data sheet Product ICK BGA 40 x 40



Heatsinks and active heatsinks for processors>Heatsinks for BGAs
40 x 40 x 6 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	40 mm
height:	6 mm
plate thickness:	1.8 mm
length:	40 mm
thermal resistance:	14.6 - 5.8 K/W
dissipation loss:	4.3 W
surface:	black anodised

Technical Drawing

